


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/21/12753	
1.3 Title of PCN	STL260N4F7, STL220N6F7 (OD48, OD68): Activation of TFME (TongFu former Nantong Fujitsu) as Second Source of Assembly and Final Testing	
1.4 Product Category	see list	
1.5 Issue date	2021-05-31	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Mario ASTUTI
2.1.2 Marketing Manager	Anna RANIOLO, Michele SCUTO
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Subcontractor TFME (TongFu former Nantong Fujitsu) - CHINA

4. Description of change

	Old	New
4.1 Description	ST Shenzhen Assy/Final Testing	ST Shenzhen - Assembly and Final Testing Subcontractor TFME (TongFu former Nantong Fujitsu) - Assembly and Final Testing Transfer introduces: - Mold Compound Hitachi CEL9220HF10
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	Capacity Increase
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Dedicated Finished Good Codes
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7. Timing / schedule

7.1 Date of qualification results	2021-07-30
7.2 Intended start of delivery	2021-08-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)		
12753 Public product.pdf 12753 Preliminary data.zip 12753 Details.pdf		
10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STL220N6F7	
	STL260N4F7	

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PRODUCT/PROCESS CHANGE NOTIFICATION

TITLE	STL260N4F7, STL220N6F7 (OD48, OD68): Activation of TFME (TongFu former Nantong Fujitsu) as second source of Assembly and Final Testing
IMPACTED PRODUCTS	see list
MANUFACTURING STEP	Assembly and Final Testing
INVOLVED PLANT	Subcontractor TFME (TongFu former Nantong Fujitsu) - China
CHANGE REASON	Capacity Increase
CHANGE DESCRIPTION	TFME (TongFu former Nantong Fujitsu) will be activated as second source of Assembly and Final Testing
TRACEABILITY	Internal traceability
VALIDATION	<p>According to AEC-Q101 and ZVEI guidelines</p> <p>ZVEI change ID:</p> <p>SEM-PA-11 - Change of mold compound / encapsulation material SEM-PA-18 - Move all or part of production to a different assembly site SEM-TF-01 - Move all or part of electrical wafer test and/or final test to a different assembly site</p>
IMPLEMENTATION	<p>Qualification will be completed with July 2021. Starting from August 2021 change will be implemented.</p> <p>Additional details and Qualification Plan included in Preliminary data.zip</p>



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : STL260N4F7, STL220N6F7 (OD48, OD68): Activation of TFME (TongFu former Nantong Fujitsu) as Second Source of Assembly and Final Testing

PCN Reference : ADG/21/12753

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STL260N4F7	STL220N6F7	
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